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TITLE: SEMICONDUCTOR DEVICE
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INVENTOR-INFORMATION:
NAME
KARASAWA, KUNIIHIKO

ASSIGNEE-INFORMATION:
NAME MITSUBISHI ELECTRIC CORP
COUNTRY N/A

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ABSTRACT:

PURPOSE: To achieve efficiency and accuracy in identifying work by providing an identifying mark with a coloring material on an integrated circuit chip which is sealed with transparent resin and the like.

CONSTITUTION: A one-pin indicating mark 6 is provided on an IC chip 2 by using a coloring material. Then, the IC chip 2 is bonded on a die pad 1 by using solder or resin. Bonding wires 3 are wired in order to connect the terminal of the IC chip 2 and lead wires 4 electrically. The device is contained in a metal mold. A transparent resin 5 is injected into the metal mold, and a package is formed. An identifying mark such as, e.g. a one-pin indicating mark, is provided on the integrated circuit chip by using the coloring material in this way. Therefore, the position of one pin can be accurately judged. Inverse introduction of the pin of the integrated circuit chip can be prevented. Thus the identifying work of the semiconductor devices can be made simple and accurate.

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